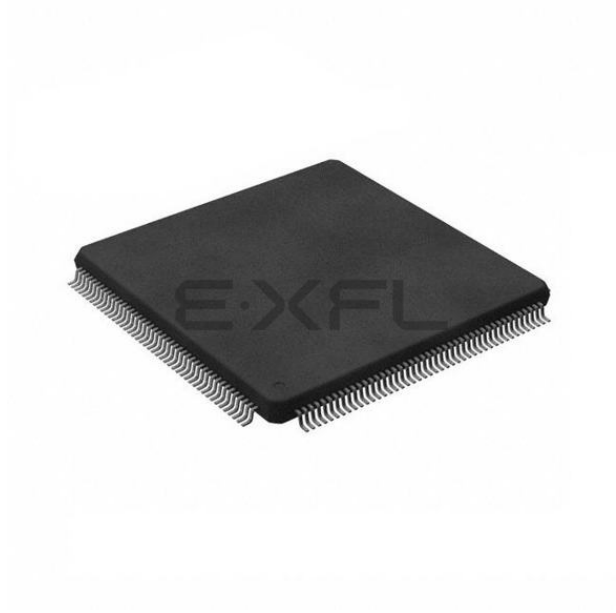

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	180MHz
Connectivity	CSIO, EBI/EMI, I²C, LINbus, SmartCard, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	153
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2g38j0agv2000a

S6E2G Series

32-bit ARM® Cortex®-M4F FM4 Microcontroller

S6E2G Series are FM4 devices with up to 180 MHz CPU, 1 MB flash, 192 KB SRAM, 20x communication peripherals, 33x digital peripherals and 3x analog peripherals. They are designed for industrial automation and metering applications.

Devices in the S6E2G Series are highly integrated 32-bit microcontrollers with high performance and competitive cost. This series is based on the ARM Cortex-M4F processor with on-chip flash memory and SRAM. The series has peripherals such as motor control timers, A/D converters, and communications interfaces (USB, CAN, UART, CSIO (SPI), I^2C, LIN). The products that are described in this data sheet are placed into TYPE5-M4 product categories in the "FM4 Family Peripheral Manual Main Part (002-04856)".

- 32-bit ARM Cortex-M4F Core
  - Up to 180 MHz frequency operation
- On-chip Memories
  - Flash memory: Up to 1024 Kbytes
  - SRAM memory:
    - SRAM0: up to 128 Kbytes
    - SRAM1: 32 Kbytes
    - SRAM2: 32 Kbytes
- Direct Memory Access (DMA) Controller (Eight Channels)
- Descriptor System Data Transfer Controller (DSTC); 256 channels
- External Bus Interface
- USB Interface (Max two channels): Host and Device
- CAN Interface (Max one channel) Available on S6E2GM and S6E2GH Devices Only
- Multi-function Serial Interface (Max 10 Channels)
  - UART (Universal Asynchronous Receiver/Transmitter)
  - Clock Synchronous Serial Interface (CSIO (SPI))
  - Local Interconnect Network (LIN)
  - Inter-Integrated Circuit (I^2C)
  - Inter-IC Sound (I^2S)
- Base Timer (Max 16 channels)
- General Purpose I/O Port
  - Up to 121 high-speed general-purpose I/O ports in 144-pin package
  - Up to 153 high-speed general-purpose I/O ports in 176-pin package
- Multi-function Timer (Max two units)
- Real-Time Clock (RTC)
- Analog to Digital Converter (ADC) (Max 32 Channels)
- Dual Timer (32-/16-bit Down Counter)
- Quadrature Position/Revolution Counter (QPRC; Max two channels)
- Watch Counter
- External Interrupt Controller Unit
- Watchdog Timer (Two channels)
- Cyclic Redundancy Check (CRC) Accelerator
- SD Card Interface Available on S6E2GM, S6E2GH, and S6E2GK Devices Only
- Ethernet-MAC Available on S6E2GM, S6E2GK, and S6E2G2 Devices only
- Smartcard Interface (Max 2 channels)
- Five Clock Sources
- Six Reset Sources
- Clock Supervisor (CSV)
- Low-Voltage Detector (LVD)
- Six Low-power Consumption Modes
  - Sleep
  - Timer
  - RTC
  - Stop
  - Deep standby RTC
  - Deep standby stop
- Peripheral Clock Gating System
- Crypto Assist Function
- Debug
  - Serial wire JTAG debug port (SWJ-DP)
  - Embedded trace macrocells (ETM) provide comprehensive debug and trace facilities.
  - AHB trace macrocells (HTM)
- 41-bit Unique ID
- Wide range voltage: VCC = 2.7 to 5.5 V

Description			Product Name				
			S6E2GM6 S6E2GM8	S6E2GK6 S6E2GK8	S6E2GH6 S6E2GH8	S6E2G36 S6E2G38	S6E2G26 S6E2G28
Base timer (PWC/Reload timer/PWM/PPG)			16 ch (Max)				
MF timer	A/D activation compare	6 ch	2 units (Max)				
	Input capture	4 ch					
	Free-run timer	3 ch					
	Output compare	6 ch					
	Waveform generator	3 ch					
	PPG	3 ch					
Smartcard (ISO7816)			2 ch (Max)				
QPRC			2 ch (Max)				
Dual timer			1 unit				
Real-time clock			1 unit				
Watch counter			1 unit				
CRC accelerator			Yes (fixed)				
Watchdog timer			1 ch (SW) + 1 ch (HW)				
External interrupts			32 pins (Max)+ NMI × 1				
CSV (clock supervisor)			Yes				
LVD (low-voltage detector)			2 ch				
Built-in CR	High-speed		4 MHz				
	Low-speed		100 kHz				
Debug function			SWJ-DP/ETM/HTM				
Unique ID			Yes				

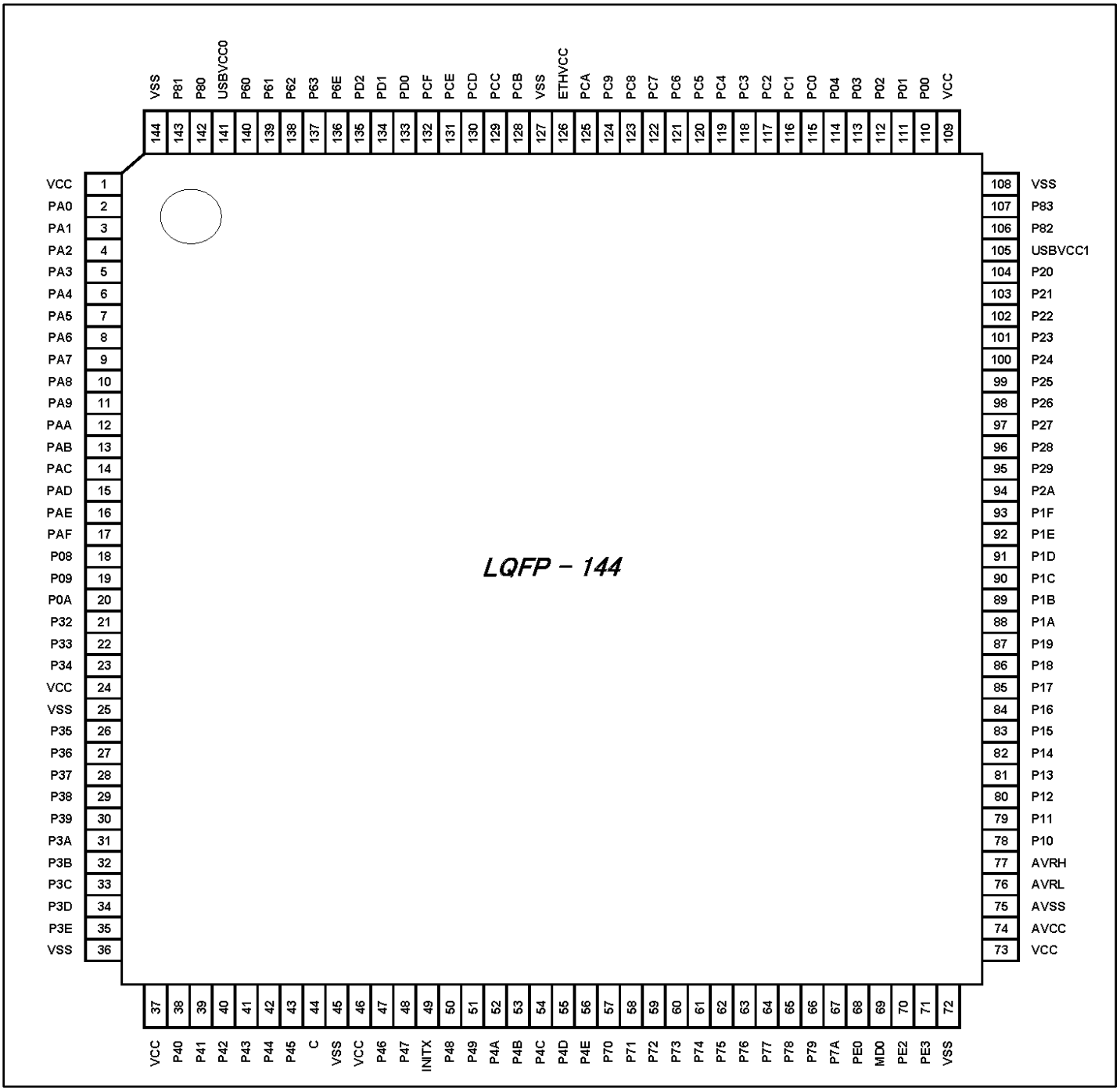
*1: Crypto Assist Function is built in following products.
S6E2GM6HHA, S6E2GM8HHA, S6E2GM6JHA, S6E2GM8JHA

Notes:

- *Because of package pin limitations, not all functions within the device can be brought out to external pins. You must carefully work out the pin allocation needed for your design.*
  You must use the port relocate function of the I/O port according to your function use.
- *See 12.4.3 Built-In CR Oscillation Characteristics for the accuracy of the built-in CR.*

5. Pin Assignments

LQS144



Note:

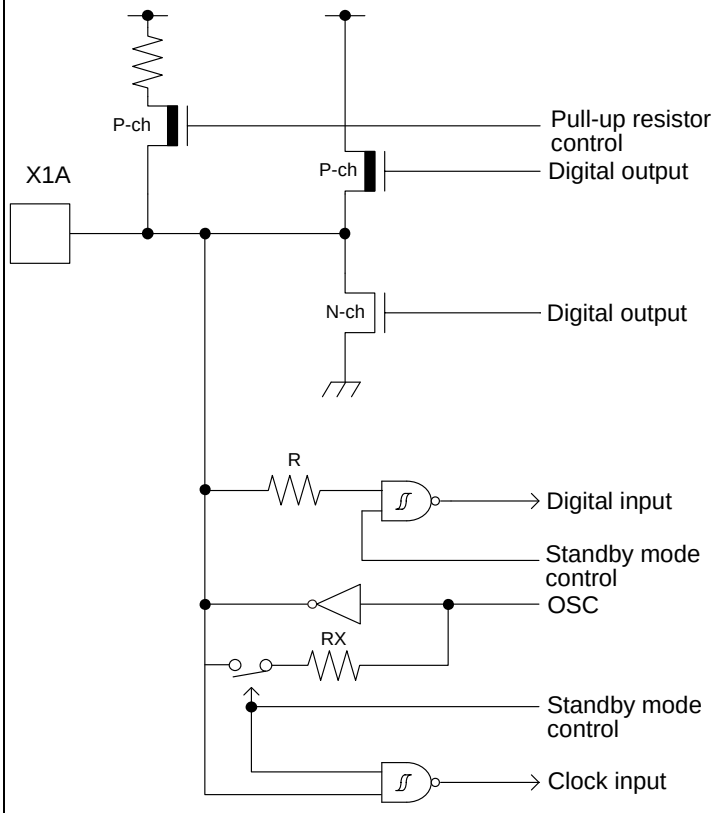
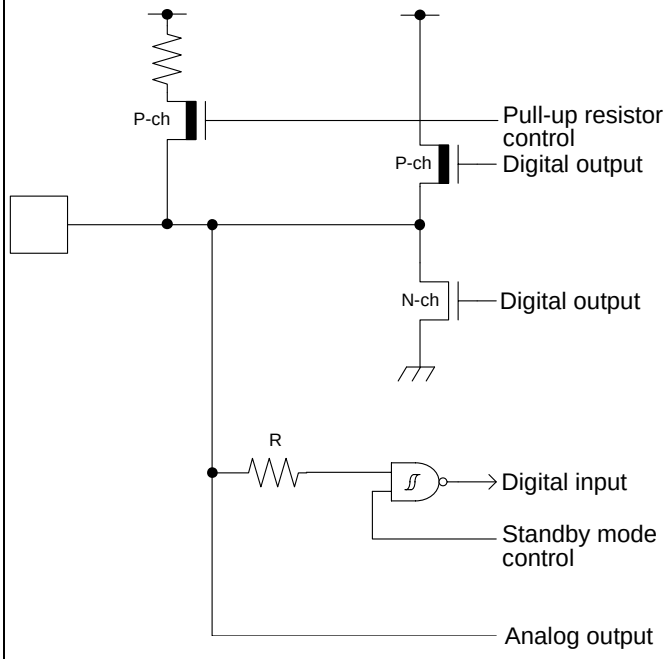
- *Only the GPIO function is shown on GPIO pins. See the table in Pin Descriptions for the full, multiplexed signal name.*

Pin Number		Pin Name	I/O Circuit Type	Pin State Type
LQFP-176	LQFP-144			
58	-	PF0	E	K
		SCS73_1		
		RX0_2		
		TIOA15_1		
		INT22_1		
59	-	PF1	E	K
		TX0_2		
		TIOB15_1		
		INT23_1		
60	50	P48	L	K
		SIN1_0		
		MI2SDI1_0		
		DTTI1X_0		
		INT06_0		
		MRASX_0		
61	51	P49	L	I
		SOT1_0 (SDA1_0)		
		MI2SDO1_0		
		IC10_0		
		MCASX_0		
62	52	P4A	L	I
		SCK1_0 (SCL1_0)		
		MI2SCK1_0		
		IC11_0		
		MSDWEX_0		
63	53	P4B	L	K
		MI2SWS1_0		
		IC12_0		
		INT04_2		
		MCSX8_0		
64	54	P4C	L	K
		MI2SMCK1_0		
		IC13_0		
		INT05_2		
		MSDCKE_0		
65	55	P4D	L	K
		FRCK1_0		
		INT07_0		
		MSDCLK_0		

Pin Number		Pin Name	I/O Circuit Type	Pin State Type
LQFP-176	LQFP-144			
83	-	PF7	E	K
		SCK3_1 (SCL3_1)		
		IC13_1		
		TIOB14_1		
		INT21_1		
		IC1_CIN_1		
84	68	PE0	C	E
		MD1		
85	69	MD0	J	D
86	70	PE2	A	A
		X0		
87	71	PE3	A	B
		X1		
88	72	VSS	-	-
89	73	VCC	-	-
90	74	AVCC	-	-
91	75	AVSS	-	-
92	76	AVRL	-	-
93	77	AVRH	-	-
94	78	P10	F	M
		AN00		
		TIOA0_2		
		INT08_0		
		MNREX_0		
		IC1_CLK_0		
95	79	P11	F	L
		AN01		
		TIOB0_2		
		MNWEX_0		
		IC1_VCC_0		
96	80	P12	F	L
		AN02		
		TIOA1_2		
		MNCLE_0		
		IC1_VPEN_0		
97	81	P13	F	M
		AN03		
		SIN9_1		
		TIOB1_2		
		INT25_1		
		MNALE_0		
		IC1_RST_0		

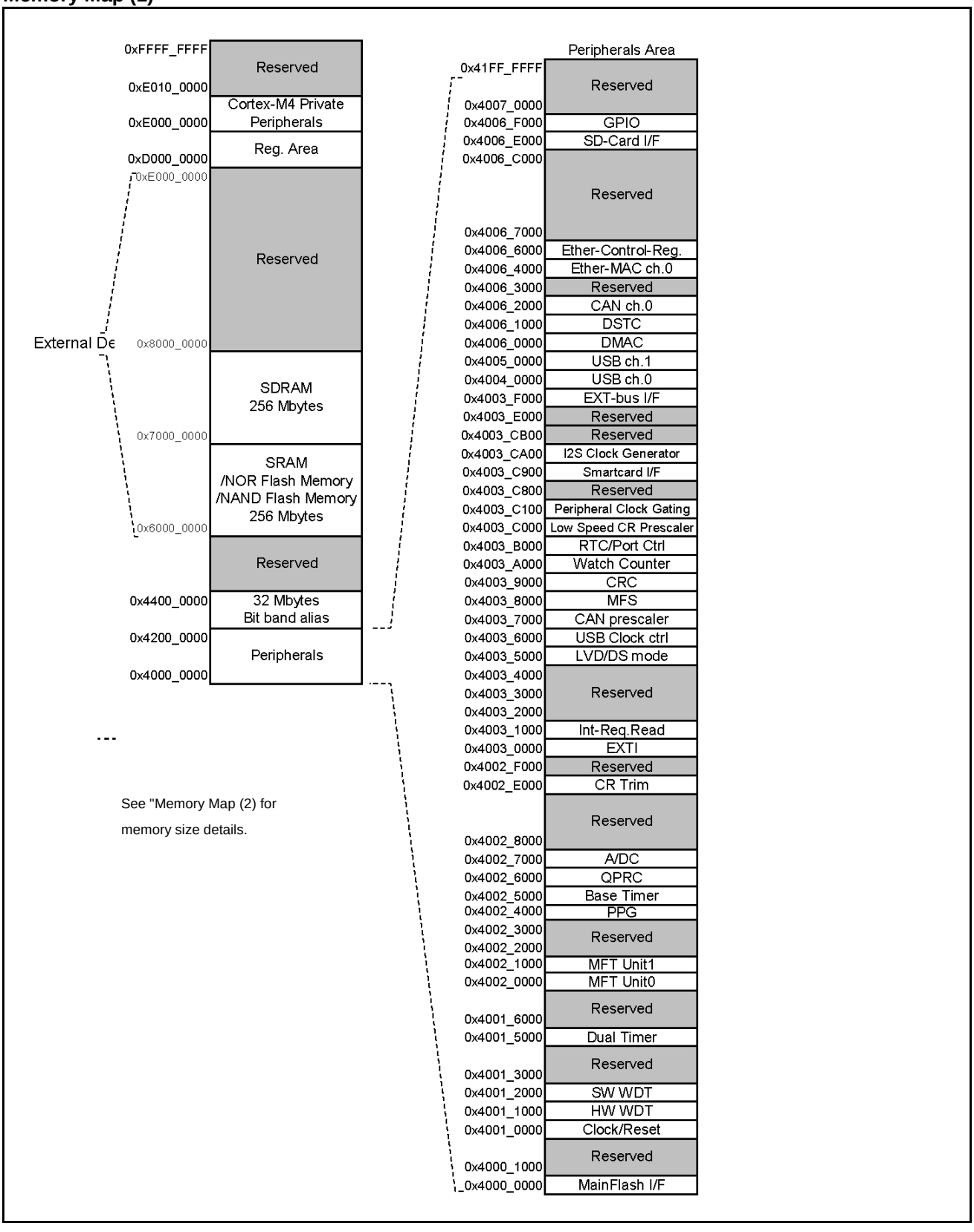
Pin Number		Pin Name	I/O Circuit Type	Pin State Type
LQFP-176	LQFP-144			
112	-	PB6	F	N
		AN22		
		SOT8_1 (SDA8_1)		
		TIOA12_1		
		BIN1_2		
		TRACED14		
113	-	PB7	F	N
		AN23		
		SCK8_1 (SCL8_1)		
		TIOB12_1		
		ZIN1_2		
		TRACED15		
114	90	P1C	F	N
		AN12		
		SCK0_1 (SCL0_1)		
		TIOA5_2		
		TRACECLK		
115	91	P1D	F	L
		AN13		
		SOT0_1 (SDA0_1)		
		TIOB5_2		
		MAD09_0		
116	92	P1E	F	M
		AN14		
		SIN0_1		
		TIOA8_1		
		INT26_1		
		MAD10_0		
117	93	P1F	F	M
		AN15		
		RTS5_0		
		TIOB8_1		
		INT27_1		
		MAD11_0		
118	94	P2A	F	M
		AN24		
		CTS5_0		
		INT08_2		
		MAD12_0		

Module	Pin Name	Function	Pin Number	
			LQFP 176	LQFP 144
SD I/F	S_CLK_0	SD memory card interface SD memory card clock output pin	28	23
	S_CMD_0	SD memory card interface SD memory card command output	31	26
	S_DATA1_0	SD memory card interface SD memory card data bus	26	21
	S_DATA0_0		27	22
	S_DATA3_0		32	27
	S_DATA2_0		33	28
	S_CD_0	SD memory card interface SD memory card detection pin	35	30
	S_WP_0	SD memory card interface SD memory card write protection	34	29
Ethernet	E_COL	Collision detection	154	124
	E_COUT	Clock output for Ethernet PHY	158	128
	E_CRS	Carrier detection	155	125
	E_MDC	Management clock	152	122
	E_MDIO	Management data I/O	151	121
	E_PPS	PTP counter monitor	166	136
	E_RX00	Received data0	149	119
	E_RX01	Received data1	148	118
	E_RX02	Received data2	147	117
	E_RX03	Received data3	146	116
	E_RXCK_REFCK	Received clock input/ Reference clock	153	123
	E_RXDV	Received data enable	150	120
	E_RXER	Received data error detection	145	115
	E_TCK	Transition clock input	159	129
	E_TX00	Transition data0	164	134
	E_TX01	Transition data1	163	133
	E_TX02	Transition data2	162	132
	E_TX03	Transition data3	161	131
	E_TXEN	Transition data enable	165	135
	E_TXER	Transition data error detection	160	130

Type	Circuit	Remarks
Q		It is possible to select the sub oscillation/GPIO function. When the sub oscillation is selected: ・ Oscillation feedback resistor: approximately 10 MΩ When the GPIO is selected: ・ CMOS level output. ・ CMOS level hysteresis input ・ Pull-up resistor control ・ Pull-up resistor: approximately 50 kΩ ・ I_{OH} = -4 mA, I_{OL} = 4 mA
R		・ CMOS level output ・ CMOS level hysteresis input ・ Analog output ・ Pull-up resistor control ・ Standby mode control ・ Pull-up resistor: approximately 50 kΩ ・ I_{OH} = -4 mA, I_{OL} = 4 mA (4.5V to 5.5V) ・ I_{OH} = -2 mA, I_{OL} = 2 mA (2.7V to 4.5V)

10. Memory Map

Memory Map (1)



2: V_{CC} must not drop below V_{SS} - 0.5 V.

3: $USBV_{CC}0$, $USBV_{CC}1$ must not drop below V_{SS} - 0.5 V.

4: $ETHV_{CC}$ must not drop below V_{SS} - 0.5 V.

5: Ensure that the voltage does not exceed V_{CC} + 0.5V, for example, when the power is turned on.

6: The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.

7: The average output current is defined as the average current value flowing through any one of the corresponding pins for a 100-ms period.

8: The total average output current is defined as the average current value flowing through all of corresponding pins for a 100-ms period.

WARNING:

- *Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.*

Table 12-4 Typical and Maximum Current Consumption in Normal Operation (Other than PLL), Code with Data Accessing Running from Flash Memory (Flash 0 Wait-Cycle Mode and Read Access 0 Wait)

Parameter	Symbol	Pin Name	Conditions		Frequency*4	Value		Unit	Remarks
						Typ*1	Max*2		
Power supply current	I_{CC}	VCC	Normal operation *6, *7 (main oscillation)	*5	4 MHz	4.3	62	mA	*3 When all peripheral clocks are on
						3.7	61	mA	*3 When all peripheral clocks are off
			Normal operation *6 (built-in High-speed CR)	*5	4 MHz	3.5	61	mA	*3 When all peripheral clocks are on
						2.9	60	mA	*3 When all peripheral clocks are off
			Normal operation *6, *8 (sub oscillation)	*5	32 kHz	0.47	58	mA	*3 When all peripheral clocks are on
						0.46	58	mA	*3 When all peripheral clocks are off
			Normal operation *6 (built-in low-speed CR)	*5	100 kHz	0.51	58	mA	*3 When all peripheral clocks are on
						0.50	58	mA	*3 When all peripheral clocks are off

1: T_A = +25 °C, V_{CC} = 3.3 V

2: T_J = +125 °C, V_{CC} = 5.5 V

3: When all ports are input and are fixed at 0

4: Frequency is a value of HCLK when PCLK0 = PCLK1 = PCLK2 = HCLK/2

5: When operating flash 0 wait-cycle mode and read access 0 wait (FRWTR.RWT = 00, FBFCR.SD = 000)

6: With data access to a MainFlash memory.

7: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

8: When using the crystal oscillator of 32 kHz (including the current consumption of the oscillation circuit)

Table 12-6 Typical and Maximum Current Consumption in Sleep Operation (PLL), when PCLK0 = PCLK1 = PCLK2 = HCLK

Parameter	Symbol	Pin Name	Conditions	Frequency*4	Value		Unit	Remarks
					Typ*1	Max*2		
Power supply current	I_{CCS}	VCC	Sleep operation*5 (PLL)	72 MHz	32	90	mA	*3 When all peripheral clocks are on
				60 MHz	27	85	mA	
				48 MHz	23	81	mA	
				36 MHz	18	76	mA	
				24 MHz	13	71	mA	
				12 MHz	8.5	66	mA	
				8 MHz	6.9	64	mA	
				4 MHz	5.3	63	mA	
				72 MHz	15	73	mA	*3 When all peripheral clocks are off
				60 MHz	13	71	mA	
				48 MHz	11	69	mA	
				36 MHz	9.3	67	mA	
				24 MHz	7.3	65	mA	
				12 MHz	5.4	63	mA	
				8 MHz	4.7	62	mA	
				4 MHz	4.1	62	mA	

1: T_A = +25 °C, V_{CC} = 3.3 V

2: T_J = +125 °C, V_{CC} = 5.5 V

3: When all ports are input and are fixed at 0

4: Frequency is a value of HCLK when PCLK0 = PCLK1 = PCLK2 = HCLK

5: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

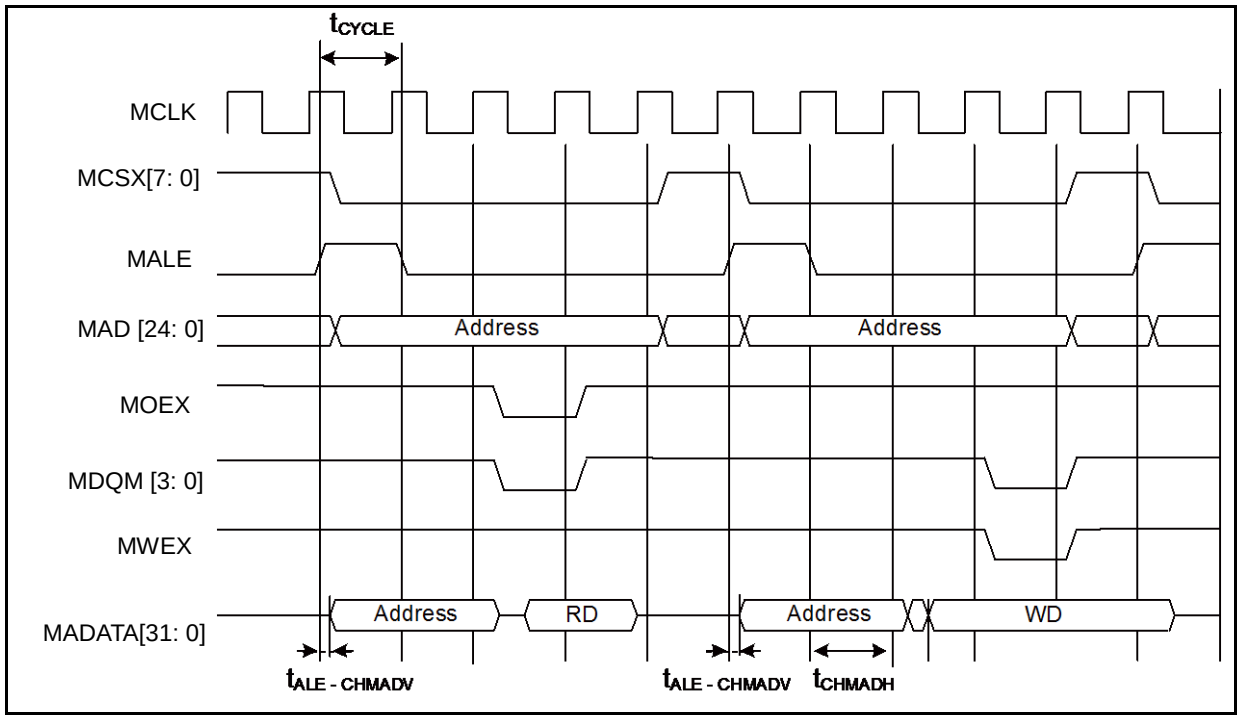
Multiplexed Bus Access Asynchronous SRAM Mode

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Multiplexed address delay time	$t_{ALE-CHMADV}$	MALE, MAD[24: 0]	-	0	10	ns	
Multiplexed address hold time	t_{CHMADH}		-	MCLK×n+0	MCLK×n+10	ns	

Note:

- *When the external load capacitance C_L = 30 pF (m = 0 to 15, n = 1 to 16)*

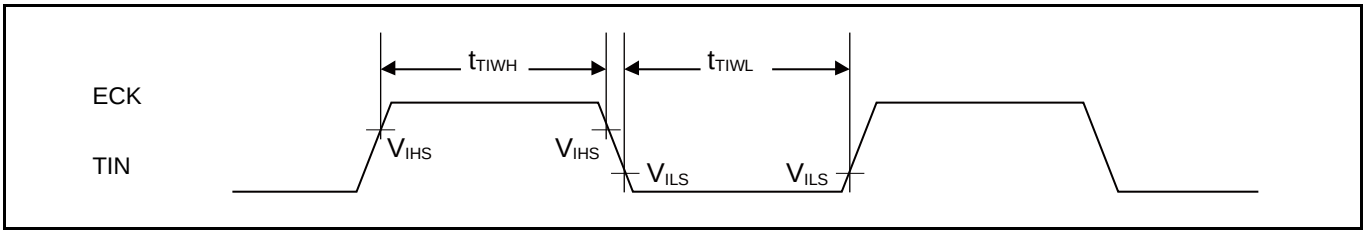


12.4.11 Base Timer Input Timing

Timer Input Timing

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

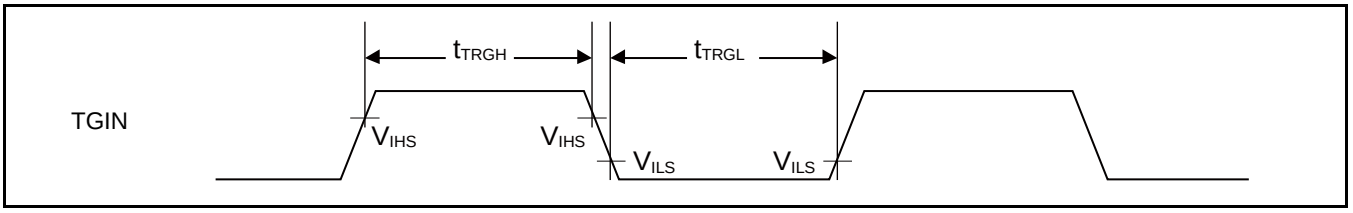
Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH}, t_{TIWL}	TIOAn/TIOBn (when using as ECK, TIN)	-	$2t_{CYCP}$	-	ns	



Trigger Input Timing

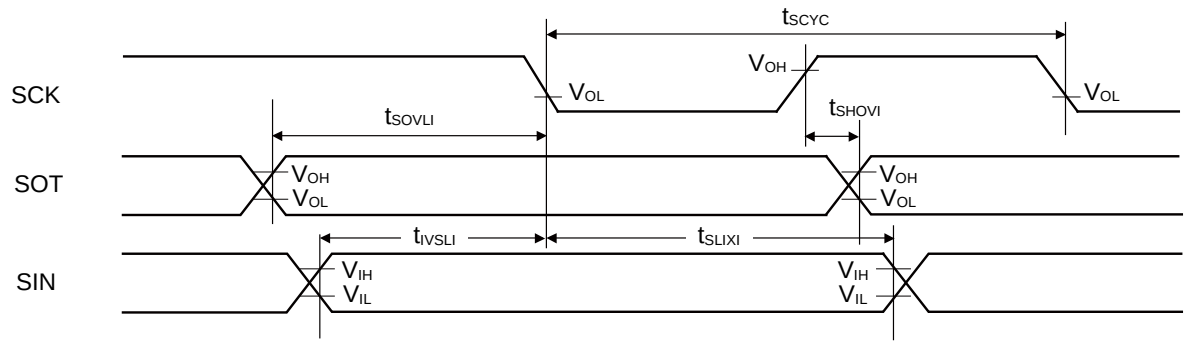
(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH}, t_{TRGL}	TIOAn/TIOBn (when using as TGIN)	-	$2t_{CYCP}$	-	ns	

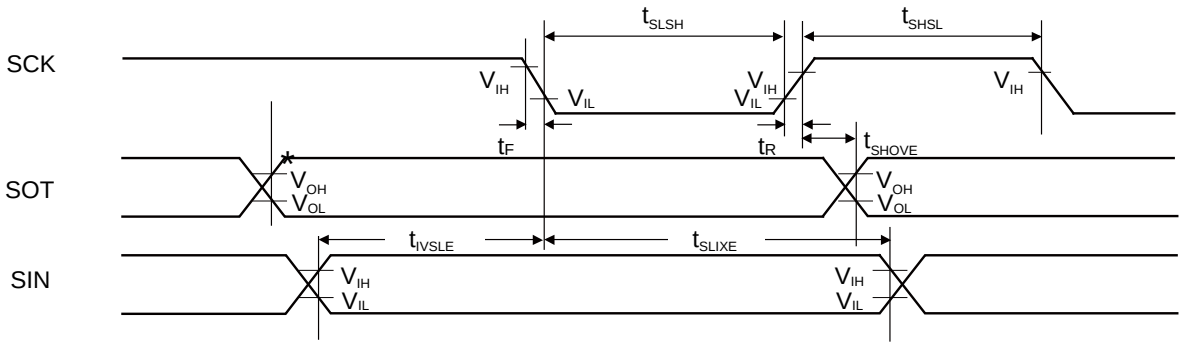


Note:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the base timer is connected, see 1. S6E2G Series Block Diagram in this data sheet.*



MS bit = 0



MS bit = 1

*: Changes when writing to TDR register

When Using High-Speed Synchronous Serial Chip Select (SCINV = 1, CSLVL = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC}≥ 4.5 V		Unit
			Min	Min	Min	Max	
SCS↓→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↑→SCS↑ hold time	t_{CSHI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t_{CSDI}		(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	ns
SCS↓→SCK↑ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCK↑→SCS↑ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCS↓→SOT delay time	t_{DSE}		-	25	-	25	ns
SCS↑→SOT delay time	t_{DEE}		0	-	0	-	ns

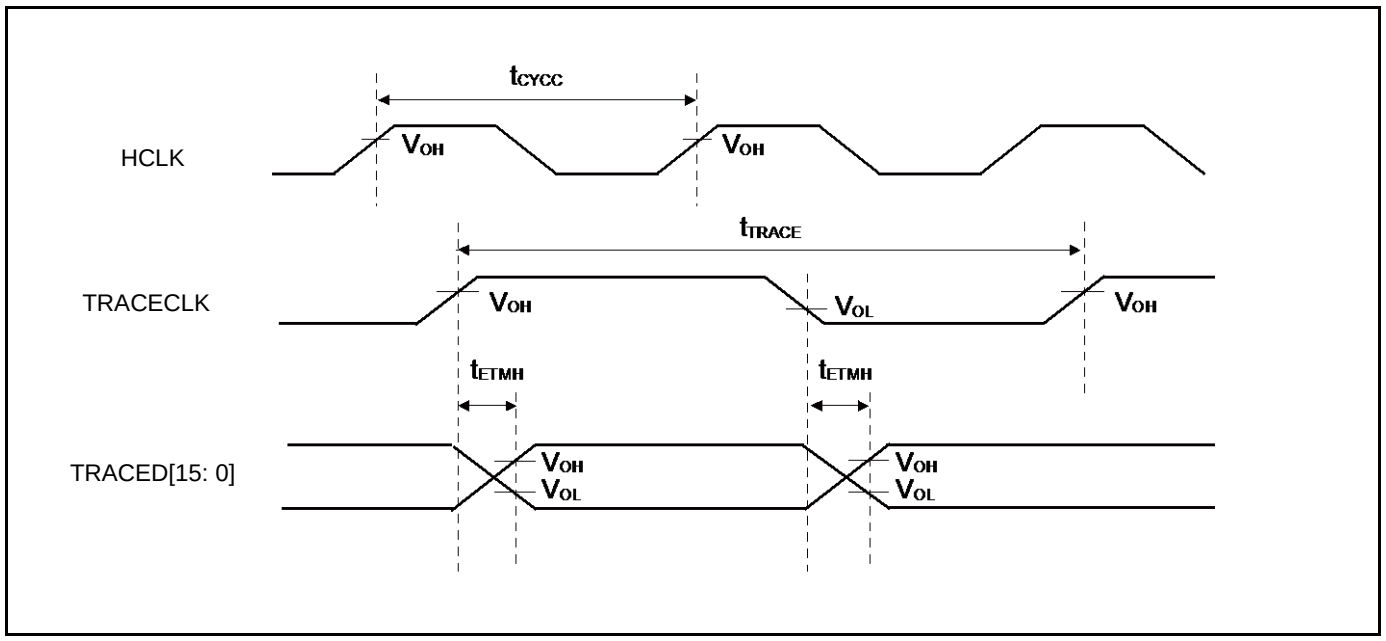
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 1. S6E2G Series Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*


tCYCC
HCLK
VOH
VOH
tTRACE
TRACECLK
VOH
VOL
VOH
tETMH
tETMH
TRACED[15: 0]
VOH
VOL
VOH
VOL

12.4.19 Ethernet-MAC Timing

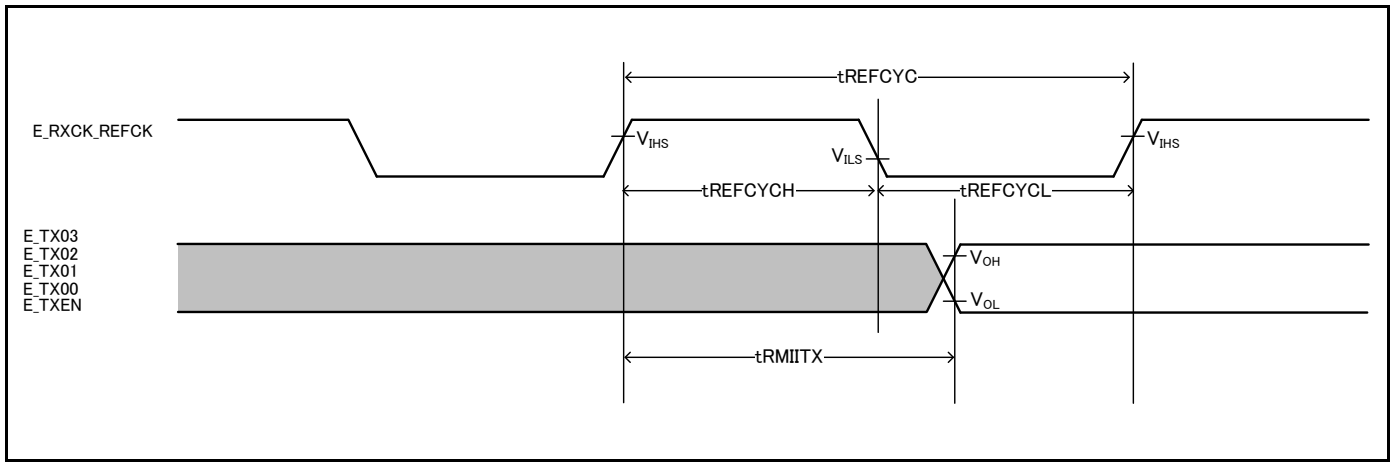
RMII Transmission (100 Mbps/10 Mbps)

($ETHV_{CC}$ = 3.0V to 3.6V, 4.5V to 5.5V*1, V_{SS} = 0V, C_L = 25 pF)

Parameter	Symbol	Pin Name	Conditions	Value		Unit
				Min	Max	
Reference clock cycle time*2	t_{REFCYC}	E_RXCK_REFCK	20 ns (typical)	-	-	ns
Reference clock High-pulse-width duty cycle	$t_{REFCYCH}$	E_RXCK_REFCK	$t_{REFCYCH}/t_{REFCYC}$	35	65	%
Reference clock Low-pulse-width duty cycle	$t_{REFCYCL}$	E_RXCK_REFCK	$t_{REFCYCL}/t_{REFCYC}$	35	65	%
REFCK ↑ → Transmitted data delay time	t_{RMIITX}	E_TX03, E_RX02, E_TX01, E_TX00, E_TXEN	-	-	12	ns

*1: When ETHV = 4.5 V to 5.5 V, it is recommended to add a series resistor at the output pin to suppress the output current.

*2: The reference clock is fixed to 50 MHz in the RMII specifications. The clock accuracy should meet the PHY-device specifications.



12.7 Low-Voltage Detection Characteristics

12.7.1 Low-Voltage Detection Reset

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	-	2.46	2.55	2.64	V	When voltage drops
Released voltage	VDH	-	2.51	2.60	2.69	V	When voltage rises

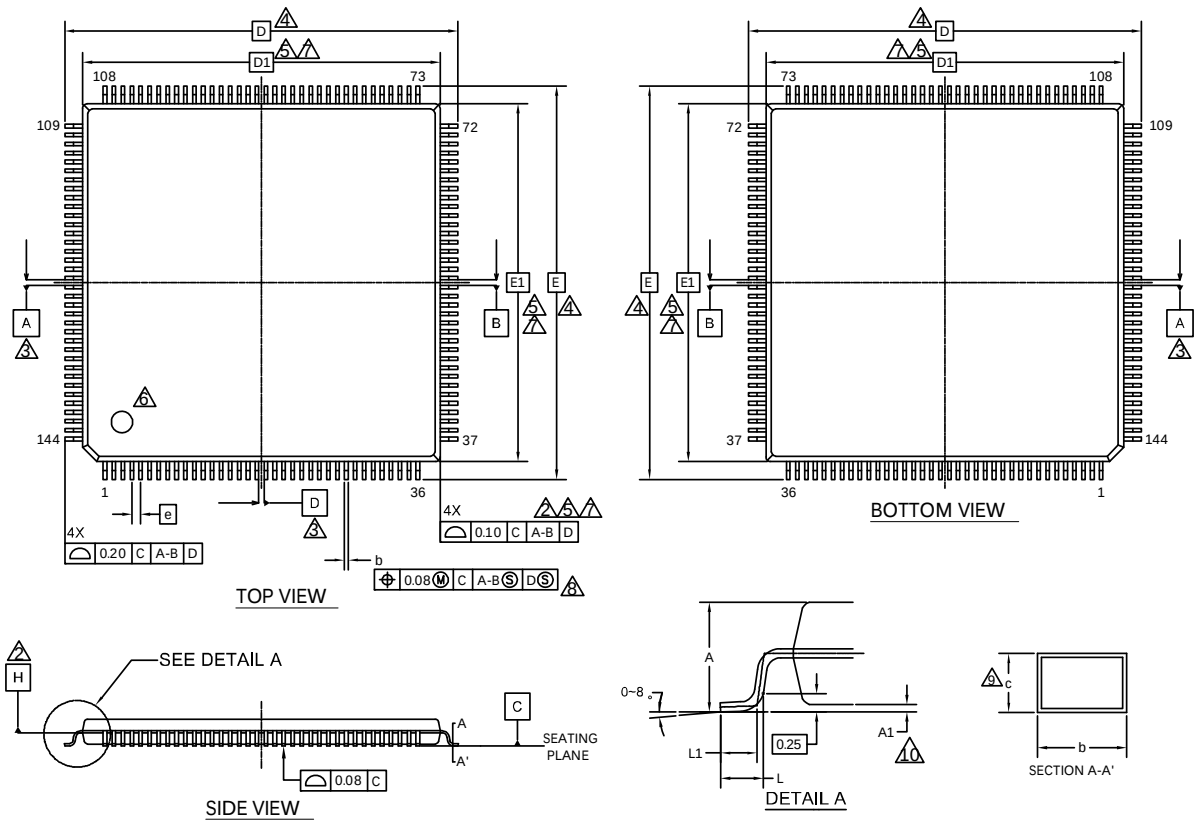
12.7.2 Interrupt of Low-Voltage Detection

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	SVHI = 00111	2.80	2.90	3.00	V	When voltage drops
Released voltage	VDH		2.90	3.00	3.11	V	When voltage rises
Detected voltage	VDL	SVHI = 00100	2.99	3.10	3.21	V	When voltage drops
Released voltage	VDH		3.09	3.20	3.31	V	When voltage rises
Detected voltage	VDL	SVHI = 01100	3.18	3.30	3.42	V	When voltage drops
Released voltage	VDH		3.28	3.40	3.52	V	When voltage rises
Detected voltage	VDL	SVHI = 01111	3.67	3.80	3.93	V	When voltage drops
Released voltage	VDH		3.76	3.90	4.04	V	When voltage rises
Detected voltage	VDL	SVHI = 01110	3.76	3.90	4.04	V	When voltage drops
Released voltage	VDH		3.86	4.00	4.14	V	When voltage rises
Detected voltage	VDL	SVHI = 01001	4.05	4.20	4.35	V	When voltage drops
Released voltage	VDH		4.15	4.30	4.45	V	When voltage rises
Detected voltage	VDL	SVHI = 01000	4.15	4.30	4.45	V	When voltage drops
Released voltage	VDH		4.25	4.40	4.55	V	When voltage rises
Detected voltage	VDL	SVHI = 11000	4.25	4.40	4.55	V	When voltage drops
Released voltage	VDH		4.34	4.50	4.66	V	When voltage rises
LVD stabilization wait time	t_{LVDW}	-	-	-	6000×t_{CYCP}*	µs	

*: t_{CYCP} indicates the APB2 bus clock cycle time.

14. Package Dimensions

Package Type	Package Code
LQFP 144	LQS144



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.05	—	0.15
b	0.17	0.22	0.27
c	0.09	—	0.20
D		22.00 BSC	
D1		20.00 BSC	
e		0.50 BSC	
E		22.00 BSC	
E1		20.00 BSC	
L	0.45	0.60	0.75
L1	0.30	0.50	0.70

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

PACKAGE OUTLINE, 144 LEAD LQFP
20.0X20.0X1.7 MM LQS144 REV*A

002-13015 *A